IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Chee Kiang Yew, et al. Art Unit (parent case):

2812

Serial No.:

TBD

Examiner (parent case): Lattin, C.W.

Filed:

Herewith

Docket:

TI-26239.1

For: Direct Attachment of Semiconductor

Chip to Organic Substrate

Conf. No.: TBD

PRELIMINARY AMENDMENT

Commissioner For Patents

Alexandria, VA 22313-1450

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that on or before this date the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Commissioner For Patents, Alexandria, VA

Sir:

Please enter the following amendment prior to examination of the instant application.

In the Specification:

Please amend the specification by inserting before the first line the sentence:

TI-26239.1 -1-